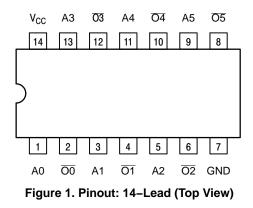
# Low-Voltage CMOS Hex Inverter with Open Drain Outputs

## With 5 V – Tolerant Inputs

The 74LVC06A is a high performance hex inverter operating from a 1.2 V to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers. These LCX devices have open drain outputs which provide the ability to set output levels, or do active–HIGH AND or active–LOW OR functions. A V<sub>I</sub> specification of 5.5 V allows 74LVC06A inputs to be safely driven from 5.0 V devices.

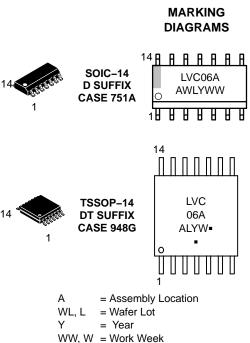
#### Features

- Designed for 1.2 V to 5.5 V  $V_{CC}$  Operation
- 5.0 V Tolerant Inputs/Outputs
- 32 mA Output Sink Capability
- Near Zero Static Supply Current (10 µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 250 mA
- Wired-OR, Wired-AND
- Output Level Can Be Set Externally Without Affecting Speed of Device
- Functionally Compatible with LCX05
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant





www.onsemi.com



G or = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

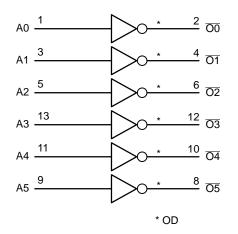


Figure 2. Logic Diagram

#### Table 1. PIN NAMES

Pins	Function
An	Data Inputs
On	Outputs

#### **Table 2. TRUTH TABLE**

An	On
L	Z

#### MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +6.5		V
VI	DC Input Voltage	$-0.5 \leq V_l \leq +6.5$		V
Vo	DC Output Voltage	$-0.5 \leq V_O \leq +6.5$	Output in 3-State	V
		$-0.5 \leq V_O \leq V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	V <sub>O</sub> > V <sub>CC</sub>	mA
Ι <sub>Ο</sub>	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds	$T_{L} = 260$		°C
TJ	Junction Temperature Under Bias	T <sub>J</sub> = 135		°C
$\theta_{JA}$	Thermal Resistance (Note 2)	SOIC = 85 TSSOP = 100		°C/W
MSL	Moisture Sensitivity		Level 1	
ILATCHUP	Latch–up Performance at V <sub>CC</sub> = 3.6 V and 125°C (Note 3)		±250	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.

I<sub>O</sub> absolute maximum rating must be observed. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow. Measured with minimum
Tested to EIA/JES078.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
74LVC06ADR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
74LVC06ADTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating Functional	1.65 1.2		5.5 5.5	V
VI	Input Voltage		0		5.5	V
V <sub>O</sub>	Output Voltage	Active Mode 3–State	0 0		V <sub>CC</sub> 5.5	V
I <sub>OL</sub>	LOW Level Output Current	$V_{CC} = 4.5 V - 5.5 V$ $V_{CC} = 3.0 V - 3.6 V$ $V_{CC} = 2.7 V - 3.0 V$ $V_{CC} = 2.3 V - 2.7 V$			+32 +24 +12 +8	mA
T <sub>A</sub>	Operating Free–Air Temperature		-40		+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 1.65 \text{ to } 2.7 \text{ V}$ $V_{CC} = 2.7 \text{ to } 5.5 \text{ V}$	0 0		20 10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

				40 to +85°	С	-4	0 to +125	°C	
Symbol	Parameter	Conditions	Min	<b>Typ</b> (Note 4)	Max	Min	<b>Typ</b> (Note 4)	Max	Unit
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 1.2 V	1.08	-	-	1.08	-	-	V
		$V_{CC}$ = 1.65 V to 1.95 V	0.65 x V <sub>CC</sub>	-	-	0.65 x V <sub>CC</sub>	-	-	
		$V_{CC}$ = 2.3 V to 2.7 V	1.7	_	-	1.7	_	-	
		$V_{CC}$ = 2.7 V to 3.6 V	2.0	-	-	2.0	_	-	
		$V_{CC}$ = 4.5 V to 5.5 V	0.7 x V <sub>CC</sub>	-	-	0.7 x V <sub>CC</sub>	-	-	
VIL	LOW-level input voltage	V <sub>CC</sub> = 1.2 V	-	-	0.12	-	-	0.12	V
		$V_{CC} = 1.65 \text{ V} \text{ to } 1.95 \text{ V}$	-	-	0.35 x V <sub>CC</sub>	-	-	0.35 x V <sub>CC</sub>	
		$V_{CC}$ = 2.3 V to 2.7 V	-	-	0.7	-	-	0.7	
		$V_{CC}$ = 2.7 V to 3.6 V	-	-	0.8	-	-	0.8	
		$V_{CC}$ = 4.5 V to 5.5 V	-	_	0.3 x V <sub>CC</sub>	-	-	0.3 x V <sub>CC</sub>	
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> o	r V <sub>IL</sub>			-	_	-	V
		I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V	-	_	0.2	-	-	0.3	
		I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V	-	-	0.45	-	-	0.65	
		$I_{O}$ = 8 mA; $V_{CC}$ = 2.3 V	-	-	0.6	-	-	0.8	
		$I_{O}$ = 12 mA; $V_{CC}$ = 2.7 V	-	-	0.4	-	-	0.6	
		$I_{O} = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.55	-	-	0.8	
		$I_{O} = 32 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	-	0.55	-	-	0.8	
lı	Input leakage current	$V_{I} = 5.5 V \text{ or GND}$ $V_{CC} = 1.65 \text{ to } 5.5 V$	-	±0.1	±5	-	±0.1	±20	μΑ
I <sub>OZ</sub>	OFF-state output current	$V_{I} = V_{IH}; V_{O} = 5.5 V \text{ or GND};$ $V_{CC} = 1.65 \text{ to } 5.5 V$	-	±0.1	±5	-	±0.1	±20	μΑ
I <sub>OFF</sub>	Power-off leakage current	$V_{I} \text{ or } V_{O} = 5.5 \text{ V}; V_{CC} = 0 \text{ V}$	-	±0.1	±10	-	±0.1	±20	μA

4. All typical values are measured at  $T_A$  = 25°C and  $V_{CC}$  = 3.3 V, unless stated otherwise.

#### DC ELECTRICAL CHARACTERISTICS

		–40 to +85°C		С	–40 to +125°C				
Symbol	Parameter	Conditions	Min	<b>Typ</b> (Note 4)	Max	Min	<b>Typ</b> (Note 4)	Max	Unit
Icc	Supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V	-	0.1	10	-	0.1	40	μΑ
ΔI <sub>CC</sub>	Additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.7 V to 5.5 V	-	5	500	-	5	5000	μΑ

4. All typical values are measured at  $T_A = 25^{\circ}C$  and  $V_{CC} = 3.3$  V, unless stated otherwise.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### AC ELECTRICAL CHARACTERISTICS ( $t_R = t_F = 2.5 \text{ ns}$ )

			-	-40 to +85°C	2	-	40 to +125°	С	
Symbol	Parameter	Conditions	Min	Typ (Note 5)	Max	Min	Typ (Note 5)	Max	Unit
t <sub>pZL</sub>	OFF-state to LOW propagation delay An	V <sub>CC</sub> = 1.2 V	-	9.0	-	-	-	-	ns
	to On	$V_{CC}$ = 1.65 V to 1.95 V	0.5	2.8	5.7	0.5	-	6.7	
		$V_{CC}$ = 2.3 V to 2.7 V	0.5	1.9	3.1	0.5	-	4.0	
		V <sub>CC</sub> = 2.7 V	0.5	1.8	3.9	0.5	-	5.0	
		$V_{CC}$ = 3.0 V to 3.6 V	0.5	1.8	3.7	0.5	-	5.0	
		$V_{CC}$ = 4.5 V to 5.5 V	0.5	1.5	2.5	0.5	-	5.0	
t <sub>pLZ</sub>	LOW to OFF-state	V <sub>CC</sub> = 1.2 V	-	10.0	-	-	-	-	ns
	propagation delay An to On	$V_{CC}$ = 1.65 V to 1.95 V	0.5	2.6	5.7	0.5	-	6.7	
		$V_{CC}$ = 2.3 V to 2.7 V	0.5	1.4	3.1	0.5	-	4.0	
		V <sub>CC</sub> = 2.7 V	0.5	2.6	3.9	0.5	-	5.0	
		$V_{CC}$ = 3.0 V to 3.6 V	0.5	2.2	3.7	0.5	_	5.0	
		$V_{CC}$ = 4.5 V to 5.5 V	0.5	1.5	2.6	-	-	3.5	

5. Typical values are measured at  $T_A$  = 25°C and  $V_{CC}$  = 3.3 V, unless stated otherwise.

#### DYNAMIC SWITCHING CHARACTERISTICS

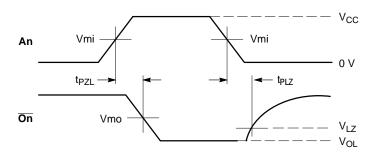
Symbol	Characteristic	Condition		Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 6)			0.8 0.6		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 6)			-0.8 -0.6		V

6. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

### **CAPACITIVE CHARACTERISTICS** ( $T_A = +25^{\circ}C$ )

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	5.0	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	6.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 7)	Per input; $V_I = GND$ or $V_{CC}$		
		V <sub>CC</sub> = 1.65 V to 1.95 V	6.5	
		$V_{CC}$ = 2.3 V to 2.7 V	6.9	
l .		V <sub>CC</sub> = 3.0 V to 3.6 V	7.2	1

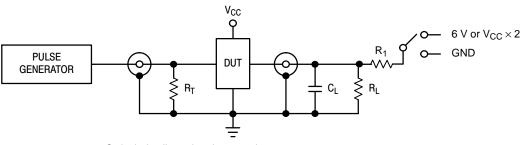
7.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W)  $P_D = C_{PD} * V_{CC}^2 x$  fi \* N + L ( $C_L x V_{CC}^2 x$  fo) where: fi = input frequency in MHz; fo = output frequency in MHz  $C_L$  = output load capacitance in pF  $V_{CC}$  = supply voltage in Volts N = number of outputs switching L ( $C_L * V_{CC}^2$ )



 $\label{eq:propagation delays} \begin{array}{l} \textbf{PROPAGATION DELAYS} \\ t_{R} = t_{F} = 2.5 \text{ ns}, \mbox{ 10\% to 90\%; f = 1 MHz; } t_{W} = 500 \text{ ns} \end{array}$ 

### Table 3. AC WAVEFORMS

	v <sub>cc</sub>							
Symbol	V <sub>CC</sub> ≥ 4.5 to 5.5 V	V <sub>CC</sub> ≥ 2.7 to 3.6 V	V <sub>CC</sub> < 2.7 V					
V <sub>mi</sub>	V <sub>CC</sub> / 2	1.5 V	V <sub>CC</sub> / 2					
V <sub>mo</sub>	V <sub>CC</sub> / 2	1.5 V	V <sub>CC</sub> / 2					
V <sub>LZ</sub>	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.15 V					

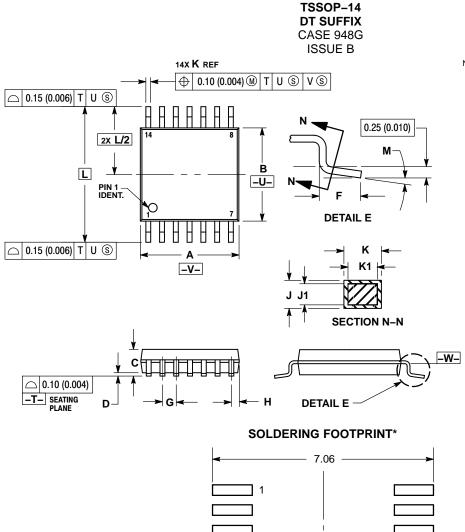


 $C_L$  includes jig and probe capacitance R<sub>T</sub> = Z<sub>OUT</sub> of pulse generator (typically 50 Q) R<sub>1</sub> = R<sub>L</sub>

#### Table 4. TEST CIRCUIT

Supply Voltage	Input		Load		V <sub>EXT</sub>		
V <sub>CC</sub> (V)	VI	t <sub>r</sub> , t <sub>f</sub>	CL	RL	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PLZ</sub> , t <sub>PZL</sub>	t <sub>PHZ</sub> , t <sub>PZH</sub>
1.2	V <sub>CC</sub>	≤ 2 ns	30 pF	1 kQ	Open	2 x V <sub>CC</sub>	GND
1.65 – 1.95	V <sub>CC</sub>	≤ 2 ns	30 pF	1 kQ	Open	$2 \times V_{CC}$	GND
2.3 – 2.7	V <sub>CC</sub>	≤ 2 ns	30 pF	500 Q	Open	$2 \times V_{CC}$	GND
2.7	2.7 V	≤ 2.5 ns	50 pF	500 Q	Open	$2 \times V_{CC}$	GND
3.0 – 3.6	2.7 V	≤ 2.5 ns	50 pF	500 Q	Open	2 x V <sub>CC</sub>	GND
4.5 to 5.5	V <sub>CC</sub>	≤ 2.5 ns	50 pF	500 Q	Open	$2 \times V_{CC}$	GND

#### PACKAGE DIMENSIONS



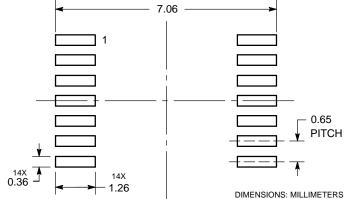
NOTES:

DTES:
DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.
DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.35 (0.010) PER SIDE.

INTERCEAD FLASH OK PROTROSION S NOT EXCEED 0.25 (0.010) PER SIDE. 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL

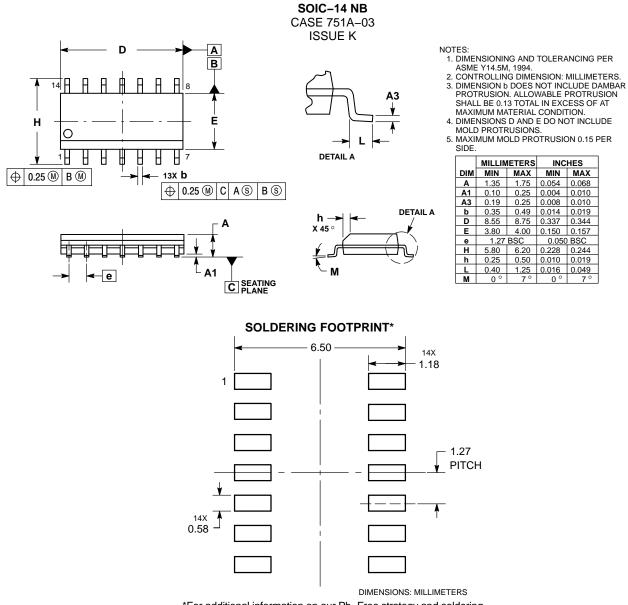
DIMENSION AI MAXIMUM MALERIAL CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
М	0 °	8 °	0 °	8 °	



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the intervent and the inter

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative